

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TSUYOSHI OGINO	02/09/2017
TAKAYUKI SEKIGUCHI	02/09/2017
KOJI OTSUKA	02/09/2017
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15412506
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DATE SIGNED:	02/27/2017
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 2	
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source=083146-0449185-DeclarationAssignment#page3.tif	

**DECLARATION (37 C.F.R. 1.63) FOR UTILITY PATENT APPLICATION USING AN
APPLICATION DATA SHEET (37 C.F.R. 1.76) AND ASSIGNMENT**

Title of Invention: **ELECTRONIC COMPONENT**

As a below named inventor, I hereby declare that:

This declaration is directed to the attached application, or (if following box is checked):

[☒] United States application or PCT international application number 15/412,506 filed on January 23, 2017.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the application, including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR Section 1.56.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

WHEREAS, the undersigned inventor(s) (hereinafter "Assignor"), has/have made an invention entitled "**ELECTRONIC COMPONENT**" disclosed in the above-identified patent application and further identified by the Attorney Docket Number provided in the header of this document, and

WHEREAS, **TAIYO YUDEN CO., LTD.** (hereinafter "Assignee"), having a place of business at 16-20, Ueno 6-chome, Taito-ku, Tokyo, 110-0005, JAPAN, is desirous of acquiring the entire right, title and interest in and to the aforesaid invention, application and all Letters Patent of the United States or any foreign country, including continuations, continuations-in-part, reissues, reexaminations, extensions, substitutes, and divisions which may be granted therefor;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration, the receipt of which is hereby acknowledged, I, the said Assignor, by these presents do sell, assign and transfer unto Assignee, its successors, legal representatives and assigns, the full and exclusive right in and to the said invention as described in the said application, and in and to any Letters Patent of the United States or any foreign country, including continuations, continuations-in-part, reissues, reexaminations, extensions, substitutes, and divisions which may be granted therefor and all rights to claim priority on the basis of said application; and I further grant to Assignee the sole right to sue and collect damages for past infringement;

AND I HEREBY authorize and request the Commissioner of Patents and Trademarks or any other proper officer or agency of any country to issue all said Letters Patent to said Assignee;

AND I HEREBY warrant and covenant that I have the full right to convey the entire interest herein assigned and that I have not executed and will not execute any instrument or assignment in conflict herewith;

AND I HEREBY agree to communicate to said Assignee or its representatives any facts known to me respecting said invention, to execute all divisional, continuation, reissue, reexamination, extension, substitute, and foreign applications, sign all lawful documents and make all rightful oaths and declarations relating to said invention, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors, legal representatives or assigns, and to testify in any judicial or administrative proceeding and generally do everything possible to aid the said Assignee to obtain and enforce said Letters Patent in the United States or any foreign country when requested so to do by said Assignee.

(1) Legal Name of Inventor: Tsuyoshi OGINO

Signature: Tsuyoshi Ogino Date: 2017/02/09
Citizenship: JAPAN

(2) Legal Name of Inventor: Takayuki SEKIGUCHI

Signature: Takayuki Sekiguchi Date: 2017/02/09
Citizenship: JAPAN

(3) Legal Name of Inventor: Koji OTSUKA

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[IF MORE INVENTORS, ADDITIONAL SIGNATURE PAGE(S) FOLLOWS]